



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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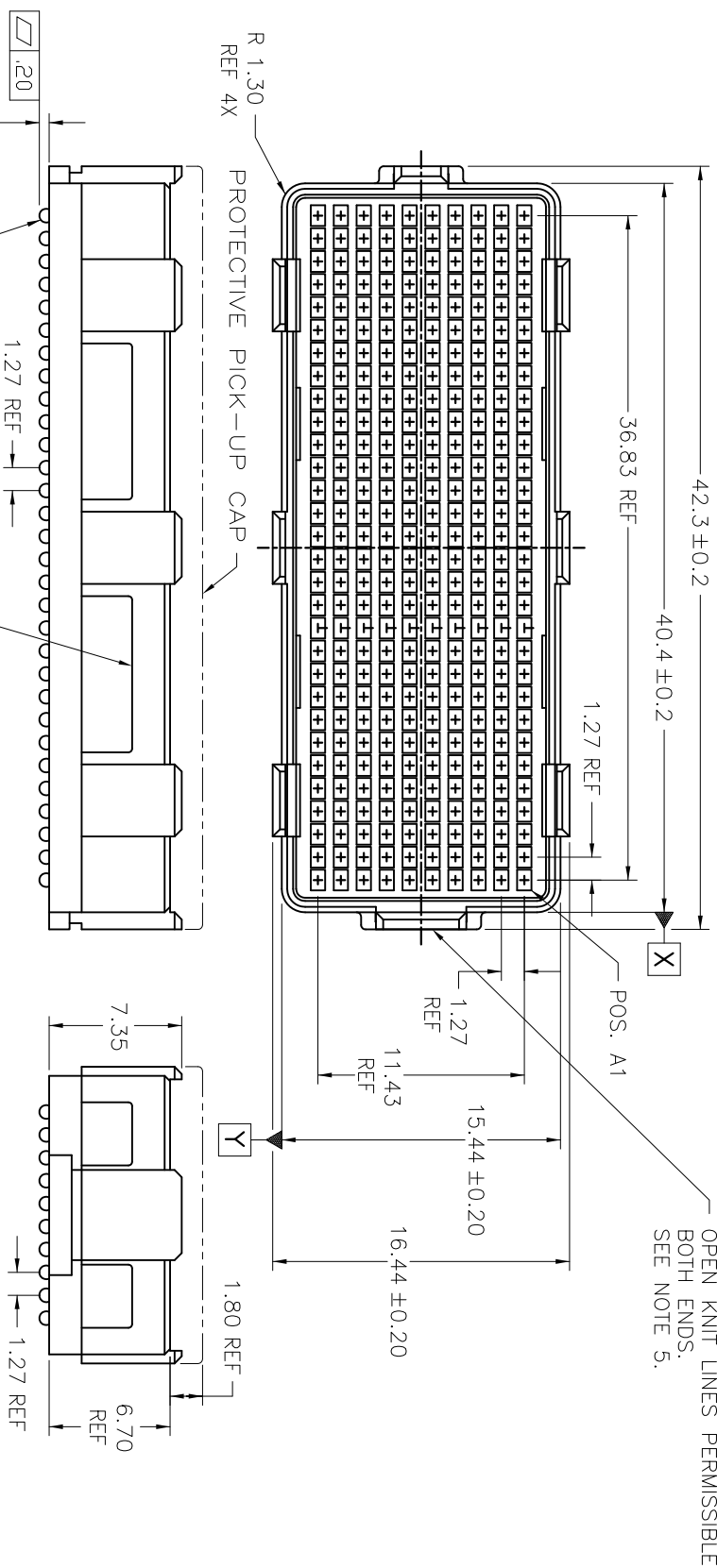


PRODUCT NUMBER
SEE TABLE-SHEET 3

1 2

3

4



NOTE 2
Ø 0.760 SOLDER BALLS
Ø .30 X Y

mat'l. code	SEE NOTE 1	surface	tolerance	projection	product family
litr	ecn no.	dtr	date	ASPE Y4.5 V	ASPE Y4.5
G	V12-0030	RE	2006-06-07	angles	X ± 3
H	V12-0046	DCH	2002-11-20	g	XX ± 18
J	V-18082	DCH	2014-6-25	0° ± 2°	XXX ± 051
-	-	-	-	dtr	D. WALUCHEN 2000-02-23
D	V04-0940	VS	2004-11-18	PLUG	W. SPINK 2000-02-23
E	V06-0560	LP	2006-07-14	CLIP	W. SPINK 2000-02-23
F	V11-0028	HTB	2016-06-02	3DD	W. SPINK 2000-02-23
Sheet	revision	J	J	J	J
Index	Sheet	1	2	3	4



product family
MEG-ARRAY

title
8.0mm RECEPTACLE ASSEMBLY
10 x 30 = 300 POS.

dwg no
84553

sheet 1 of 4

size
A4

type
CUSTOMER Drawing

PRODUCT NUMBER
SEE TABLE-SHEET-3

NOTES:

① MATERIAL:

HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET 3)
SOLDER BALL: (SEE TABLE ON SHEET 3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

② SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

③ MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

④ PLATING FOR INDICATED -2XX SERIES PRODUCT NUMBERS MEET THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY). THE CONTACTS GEOMETRY IN THESE PRODUCT NUMBERS IS SPECIAL, ALSO.

⑤ KNT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) INDICATING THE DIRECTION AND MEETING POINT OF PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.

⑥ FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

⑦ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

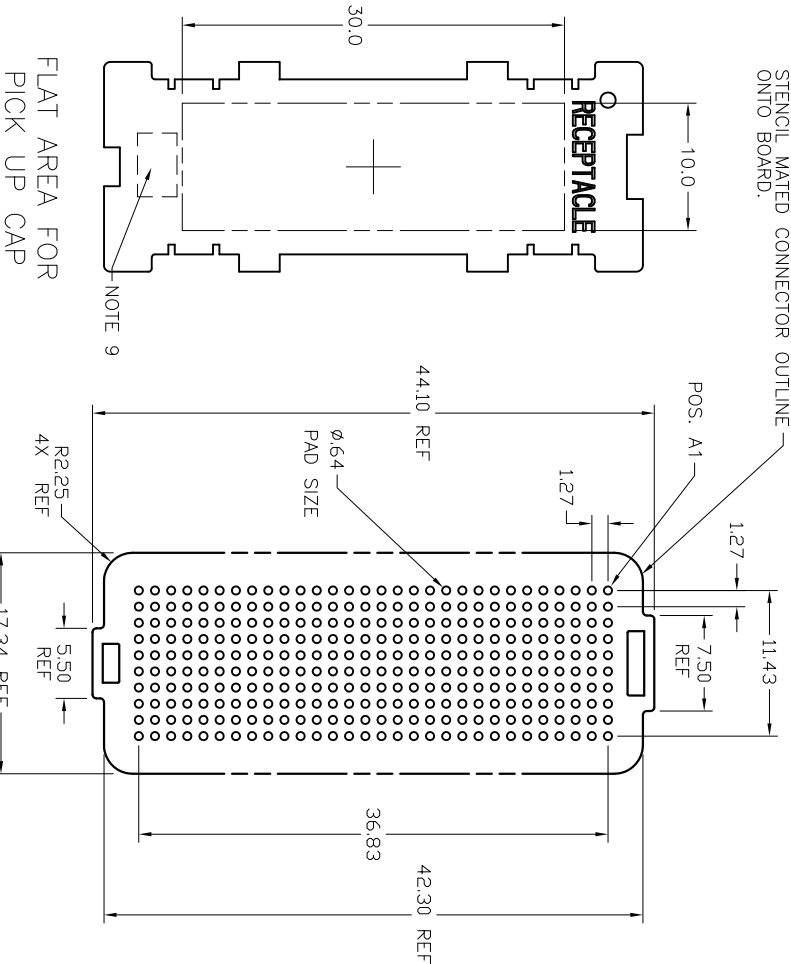
⑧ 84553-A01 AND -A01LF ARE CUSTOMER SPECIALS.


⑨ CURRENT COMPANY LOGO TO BE VISIBLE IN APPROXIMATE AREA SHOWN.

⑩ 84553-0931LF HAS A SPECIAL CAP.

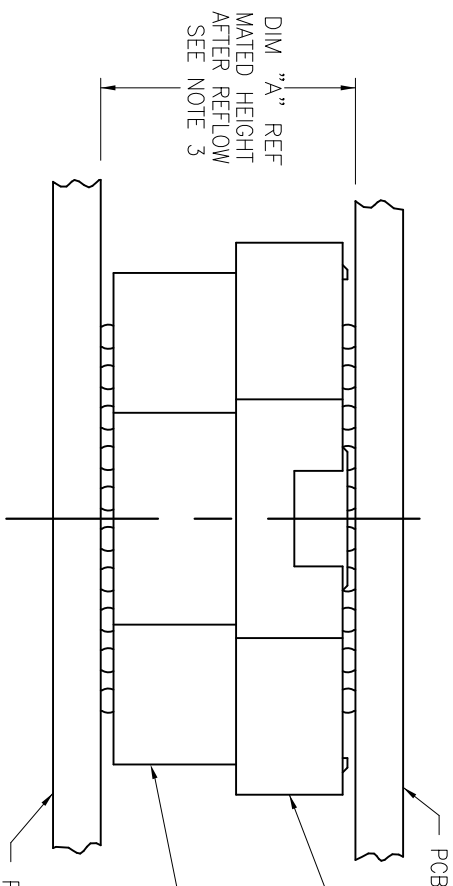
12. A  SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

STENCIL MATED CONNECTOR OUTLINE
ONTO BOARD.






mat'l. code			surface			tolerance			projection			product family					
SEE NOTE 1			ASPE Y4.5			ASPE Y4.5						MEG-ARRAY					
lfr			ecn no			dr			date			title					
						angles			X ±3			8.0mm RECEPTACLE ASSEMBLY					
J						linear			XX ±B			10 x 30 = 300 POS.					
						D ±2			XXX ±051			scale 2:1					
			dr			D. WAUGHEN			2000-02-23			dwg no					
						ENGR			W. SPINK			2000-02-23			sheet 2 of 4		
						CNC			W. SPINK			2000-02-23			size		
															A4		
						apprd			W. SPINK			2000-02-23			CUSTOMER Drawing		
sheet			revision														
index			sheet														

PRODUCT NUMBER	PICK-UP CAP (NATURAL OR BLACK COLOR)	CONTACT PLATING AND THICKNESS	SOLDER BALL	NOTES
84553--001	YES	15u" (.38um) Au	SnPb	
84553--001LF	YES	15u" (.38um) Au	LEAD FREE	7
84553--091	YES	15u" (.38um) GXT	SnPb	
84553--091LF	YES	15u" (.38um) GXT	LEAD FREE	7
84553--093LF	YES	15u" (.38um) GXT	LEAD FREE	7 , 10
84553--101	YES	30u" (.76um) Au	SnPb	
84553--101LF	YES	30u" (.76um) Au	LEAD FREE	7
84553--191	YES	30u" (.76um) GXT	SnPb	
84553--191LF	YES	30u" (.76um) GXT	LEAD FREE	7
84553--201	YES	50u" (1.27um) Au SPECIAL	SnPb	4
84553--201LF	YES	50u" (1.27um) Au SPECIAL	LEAD FREE	4 AND 7
84553--291	YES	50u" (1.27um) GXT SPECIAL	SnPb	4
84553--291LF	YES	50u" (1.27um) GXT SPECIAL	LEAD FREE	4 AND 7
84553--A01	YES	30u" (.76um)	SnPb	8
84553--A01LF	YES	30u" (.76um)	LEAD FREE	7 AND 8
84593--301	YES	15u" (.38um) Au SPECIAL	SnPb	8
84593--301LF	YES	15u" (.38um) Au SPECIAL	LEAD FREE	7 AND 8
84593--401	YES	30u" (.76um) Au SPECIAL	SnPb	8
84593--401LF	YES	30u" (.76um) Au SPECIAL	LEAD FREE	7 AND 8
84593--501	YES	Au SPECIAL	SnPb	4 AND 8
84593--501LF	YES	Au SPECIAL	LEAD FREE	4, 7 AND 8



MATED HEIGHT AFTER REFLOW IS BASED ON Ø.64mm PAD (METAL-DEFINED)
AND .13mm SOLDER PASTE THICKNESS. SEE NOTE 3.
END VIEW - MATED CONNECTORS

PLUG ASSEMBLY (SEE TABLE BELOW)	
DIM."A"	PLUG ASSY. P/N
8.0	84500
14.0	84578

mat'l. code		surface		tolerance		projection		product family	
SEE NOTE 1		ASME Y14.5 ✓		ASME Y14.5				MEG--ARRAY	
lth	ecrn no	dr	date	tolerances unless otherwise specified				title	
j				angles	X ±.3			8.0mm RECEPTACLE ASSEMBLY	
				linear	.XX ±.13			10 x 30 = 300 POS.	
				dr ±.2	XXX ±.051			dwg no	
				dr	D. WAUGHEN 2000-02-23			sheet 3 of 4	
				ENGR	W. SPINK 2000-02-23			84553	
				CTR	W. SPINK 2000-02-23			A4	
				apprd	W. SPINK 2000-02-23			CUSTOMER Drawing	
street index	revision								
	sheet								

1	2
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